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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR: Mahesh Sanganeria et al.) EXAMINER: Minh Loan Tran
SERIAL NO.: 10/647,773)
FILING DATE: August 25, 2003) ART UNIT: 2826
FOR: METHOD OF IMPROVING
ADHESION BETWEEN TWO
DIELECTRIC FILMS) DATE: October 4, 2004

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Restriction Requirement Office Action mailed September 8, 2004, applicants provisionally elect Group I, claims 1-23, drawn to a process.

The Examiner has restricted the invention of the subject application to one of the following inventions:

| | | |
|----------|--------------|---|
| Group I | Claims 1-23 | Drawn to a process for making electronic components having improving adhesion between an insulating layer and a capping layer, classified in class 438, subclass 644; and |
| Group II | Claims 24-29 | Drawn to a semiconductor structure, classified in class 257, subclass 753. |

Applicants respectfully traverse the restriction requirement on the grounds that 35 USC § 121 authorizes restriction only when the claimed invention is "independent"